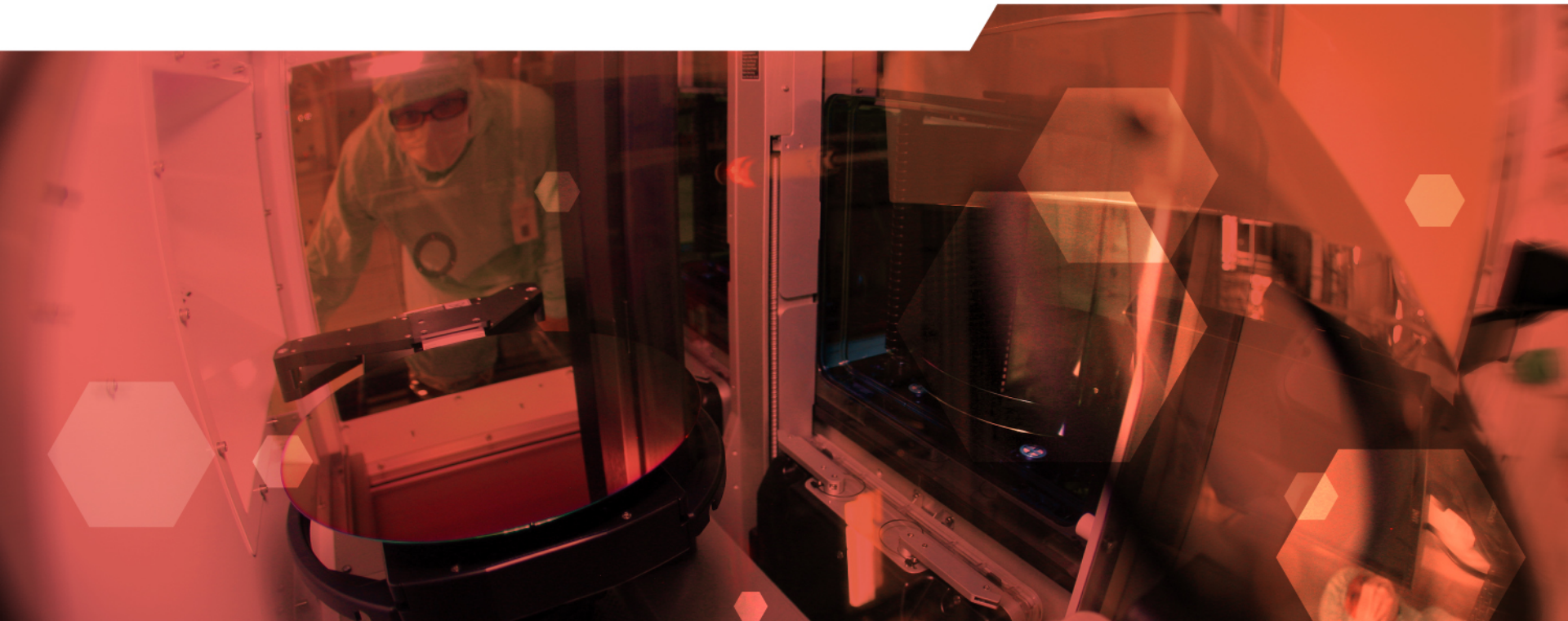


North America TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee

Liaison Report

July 2019

v1



Meeting Information

- Last meeting
 - Thursday, July 11th at the SEMICON West Standards 2019 Meetings
 - Moscone Center, San Francisco, CA/USA
- Next meeting
 - Thursday, November 7th at the NA SEMI Standards Fall 2019 Meetings
 - SEMI Headquarters, Milpitas, CA

<http://www.semi.org/en/standards-events>

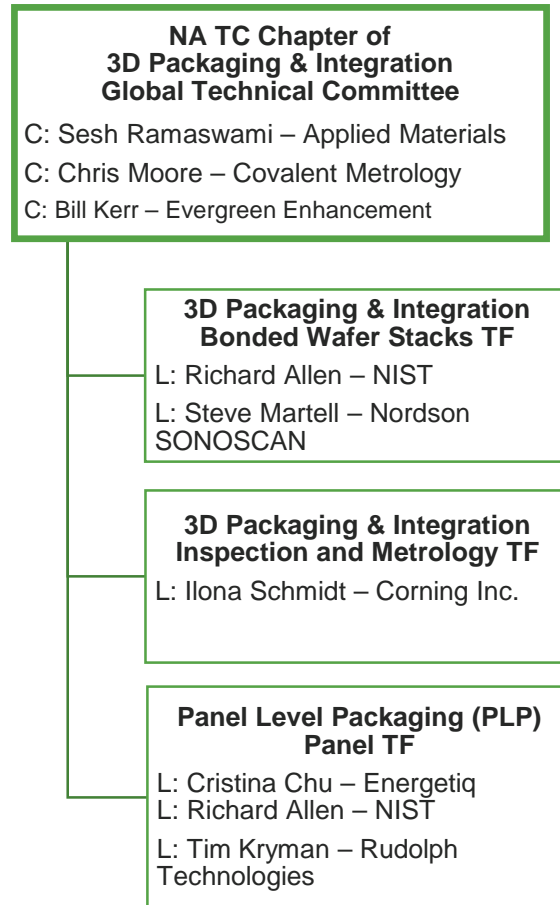
Leadership Changes

<i>TF/SC/CFG/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
3DP&I NA TC Chapter	Richard Allen - NIST (Stepped down)	Bill Kerr (Evergreen Enhancement)
Fan-Out Panel Level Packaging (FO-PLP) Panel TF		Timothy Kryman (Rudolph Technologies)

Committee Structure Changes

<i>Previous TF/SC/CFG Name</i>	<i>New TF/SC/CFG Name or Status Change</i>
Fan-Out Panel Level Packaging (FO-PLP) Panel TF	Panel Level Packaging (PLP) Panel TF

Organization Chart



Ballot Results

Doc #	Document Title	TC Chapter Action
R6075A	New Standard: Guide for Describing Glass-Based Material for Use in 3DS-IC Process	Passed , A&R Cycle 6-2019
R6332A	New Standard: Specification for Panel Substrate Characteristics for Panel Level Packaging (PLP) Applications	Passed , A&R Cycle 6-2019
6175B	New Standard: Guide on Measurements of Openings and Vias in Glass	Passed , with editorial changes
6511	Reapproval of SEMI 3D8-0514, Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process	Failed
6513	Reapproval of SEMI G83-0912, Specification for Bar Code Marking of Product Packages	Failed

#1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Authorized Activities

Doc #	Type	SC/TF/CFG	Document Title/Details
-	TFOF	PLP Panel TF	Panel Level Packaging (PLP) Panel TF – <i>Revision to TFOF: update TF name, charter and scope</i>
6555	SNARF	NA 3DP&I Committee	Reapproval of SEMI 3D9-0914, Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack – <i>Authorized new SNARF</i>
6556	SNARF	NA 3DP&I Committee	Reapproval of SEMI 3D10-0814, Guide to Describing Materials Properties for Intermediate Wafers for Use in a 300 mm 3DS-IC Wafer Stack – <i>Authorized new SNARF</i>
6557	SNARF	NA 3DP&I Committee	Reapproval of SEMI 3D11-1214, Terminology for Through Glass Via and Blind Via in Glass Geometrical Metrology – <i>Authorized new SNARF</i>
6558	SNARF	NA 3DP&I Committee	Reapproval of SEMI 3D12-0315, Guide for Measuring Flatness and Shape of Low Stiffness Wafers – <i>Authorized new SNARF</i>

#1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Authorized Ballots

Doc #	When	TF	Document Title/Details
6555	Cycle 6-2019	NA 3DP&I Committee	Reapproval of SEMI 3D9-0914, Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack
6556	Cycle 6-2019	NA 3DP&I Committee	Reapproval of SEMI 3D10-0814, Guide to Describing Materials Properties for Intermediate Wafers for Use in a 300 mm 3DS-IC Wafer Stack
6557	Cycle 6-2019	NA 3DP&I Committee	Reapproval of SEMI 3D11-1214, Terminology for Through Glass Via and Blind Via in Glass Geometrical Metrology
6558	Cycle 6-2019	NA 3DP&I Committee	Reapproval of SEMI 3D12-0315, Guide for Measuring Flatness and Shape of Low Stiffness Wafers

Abolished SNARF(s)

Doc #	TF	Title/Details
6511	NA 3DP&I Committee	Reapproval of SEMI 3D8-0514, Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process – Reapproval ballot failed Committee review, new SNARF to be issued to reflect change in scope
6513	NA 3DP&I Committee	Reapproval of SEMI G83-0912, Specification for Bar Code Marking of Product Packages – Reapproval ballot failed Committee review. This is a redundant ballot.

Task Force Highlights (1/2)

- Bonded Wafer Stacks TF and Inspection & Metrology TF met jointly
 - Reviewed ballots results as stated in previous slides.
 - New Standard: Guide on Measurements of Openings and Vias in Glass
 - Passed A&R August Cycle
 - New Standard: Guide for Describing Glass-Based Material for Use in 3DS-IC Process
 - Recently published as SEMI 3D21-0919

Task Force Highlights (2/2)

- Panel Level Packaging (PLP) Panel TF
 - Changes to TFOF: updated TF name and scope
 - Appointed new TF co-leader: Tim Kryman (Rudolph Technologies)
 - Document # R6332A, New Standard: Specification for Panel Substrate Characteristics for Panel Level Packaging (PLP) Applications, with title change to: Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications
 - Received one disapprove vote which the TF will address at the next time the document ballots.
 - Passed TC Chapter review at Spring Meetings
 - Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications
 - » Recently published SEMI 3D20-0719
 - Meets via Web & teleconference monthly to discuss next steps
 - Parameters to pull from Appendix to Requirements section of the standard
 - To be added to the distribution, please contact Laura Nguyen (Inguyen@semi.org)

Thank you!

For more information or to participate in any
3D Packaging & Integration NA activities, please contact:

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